



## PRODUCT DATA SHEET



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**Datasheet**



**Resources**



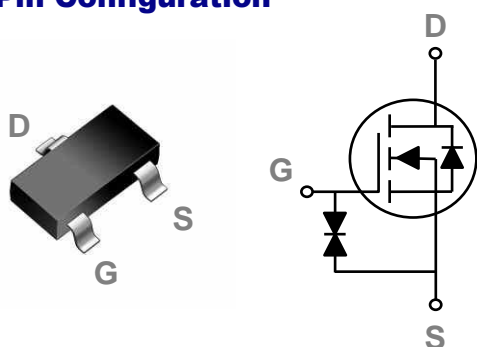
**Samples**

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.jg-semi.cn](http://www.jg-semi.cn). Please email any questions regarding the system integration to [JINGAO\\_questions@jgsemi.com](mailto:JINGAO_questions@jgsemi.com).

## General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

## SOT523 Pin Configuration



BVDSS	RDSON	ID
20V	200mΩ	800mA

## Features

- 20V,800mA,  $R_{DS(ON)} = 200m\Omega @ V_{GS} = 4.5V$
- Improved  $dv/dt$  capability
- Fast switching
- ESD protected up to 2KV
- Green Device Available

## Applications

- Notebook
- Load Switch
- Battery Protection
- Hand-held Instruments

## Absolute Maximum Ratings $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	$\pm 10$	V
$I_D$	Drain Current – Continuous ( $T_A=25^\circ\text{C}$ )	800	mA
	Drain Current – Continuous ( $T_A=70^\circ\text{C}$ )	640	mA
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	3.2	A
$P_D$	Power Dissipation ( $T_A=25^\circ\text{C}$ )	312	mW
	Power Dissipation – Derate above $25^\circ\text{C}$	2.5	mW/ $^\circ\text{C}$
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$T_J$	Operating Junction Temperature Range	-55 to 125	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	400	$^\circ\text{C/W}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =1mA	---	-0.01	---	V/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C	---	---	10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±10V , V <sub>DS</sub> =0V	---	---	±10	uA

**On Characteristics**

R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.5A	---	200	270	mΩ
		V <sub>GS</sub> =2.5V , I <sub>D</sub> =0.4A	---	235	380	
		V <sub>GS</sub> =1.8V , I <sub>D</sub> =0.2A	---	295	550	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.6	1.0	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	3	---	mV/°C

**Dynamic and switching Characteristics**

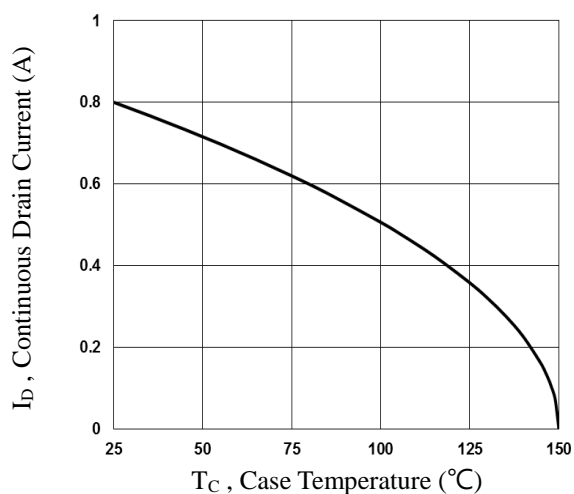
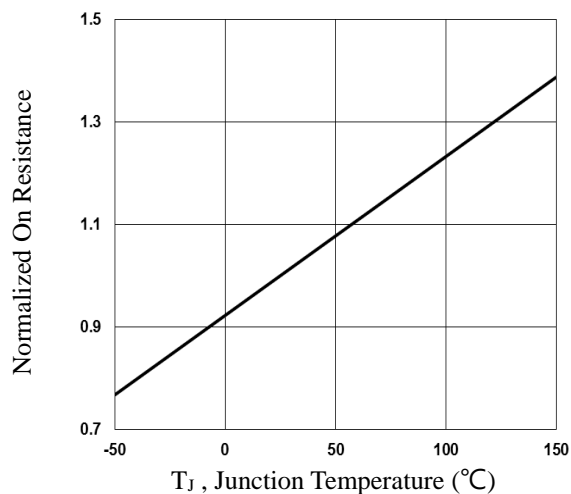
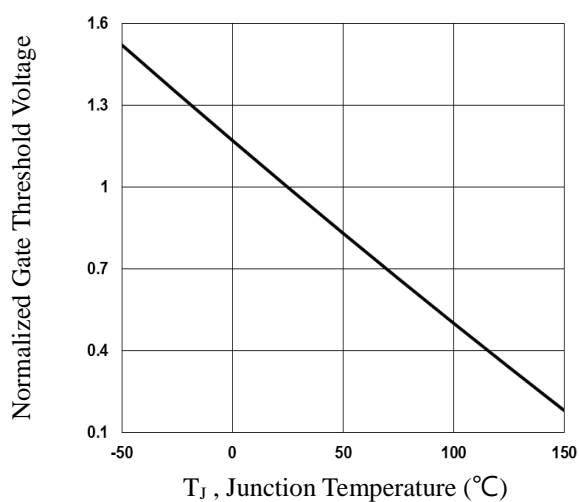
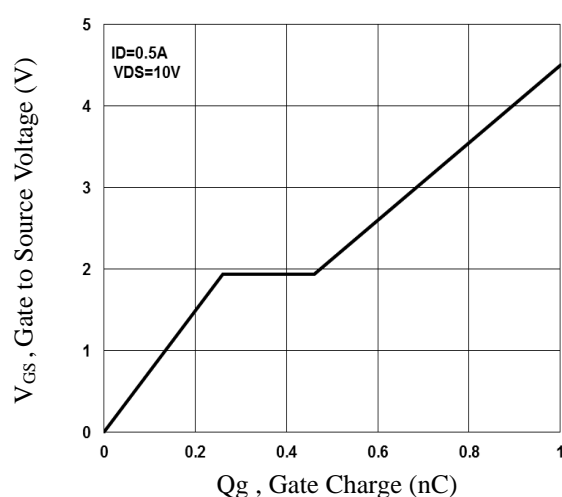
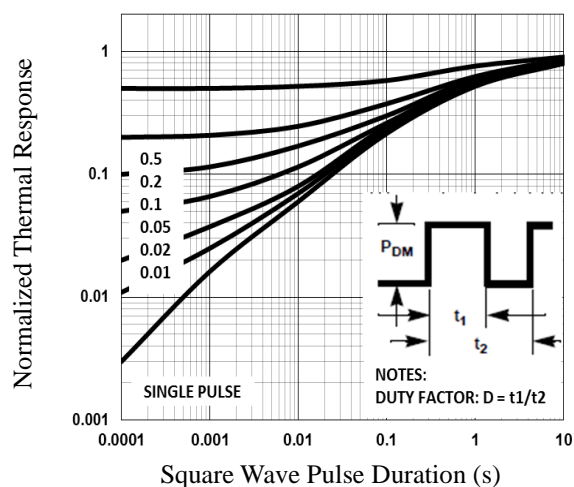
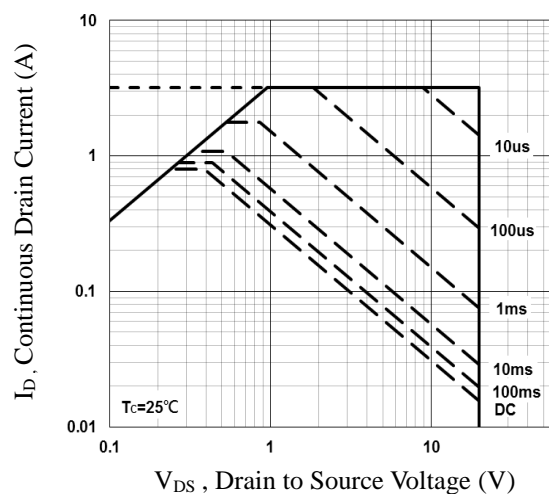
Q <sub>g</sub>	Total Gate Charge <sup>2, 3</sup>	V <sub>DS</sub> =10V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.5A	---	1	---	nC
Q <sub>gs</sub>	Gate-Source Charge <sup>2, 3</sup>		---	0.26	---	
Q <sub>gd</sub>	Gate-Drain Charge <sup>2, 3</sup>		---	0.2	---	
T <sub>d(on)</sub>	Turn-On Delay Time <sup>2, 3</sup>	V <sub>DD</sub> =10V , V <sub>GS</sub> =4.5V , R <sub>G</sub> =10Ω I <sub>D</sub> =0.5A	---	5	---	ns
T <sub>r</sub>	Rise Time <sup>2, 3</sup>		---	3.5	---	
T <sub>d(off)</sub>	Turn-Off Delay Time <sup>2, 3</sup>		---	14	---	
T <sub>f</sub>	Fall Time <sup>2, 3</sup>		---	6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V , V <sub>GS</sub> =0V , F=1MHz	---	38.2	---	pF
C <sub>oss</sub>	Output Capacitance		---	14.4	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	6	---	

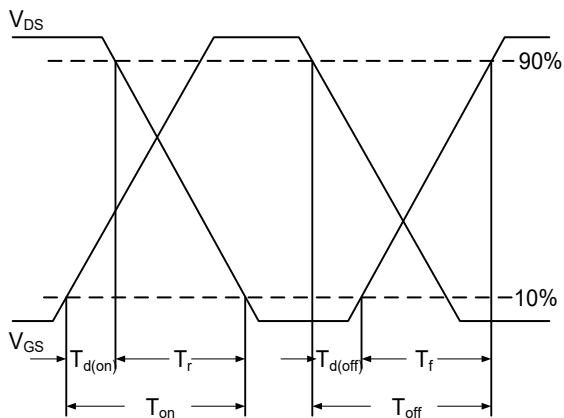
**Drain-Source Diode Characteristics and Maximum Ratings**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	0.8	A
I <sub>SM</sub>	Pulsed Source Current		---	---	1.6	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =0.2A , T <sub>J</sub> =25°C	---	---	1.2	V

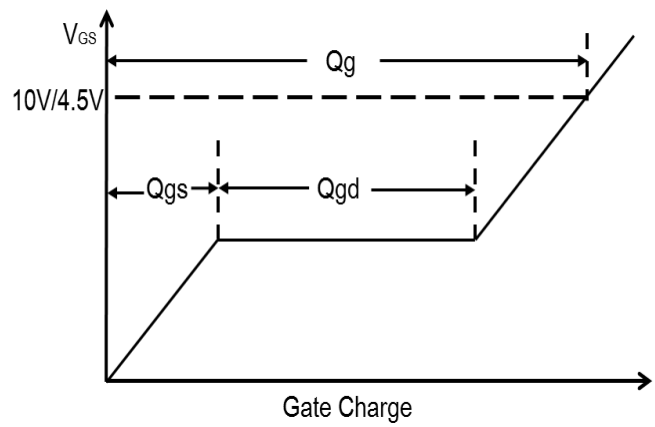
Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
3. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs.  $T_c$** 

**Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$** 

**Fig.3 Normalized  $V_{th}$  vs.  $T_j$** 

**Fig.4 Gate Charge Waveform**

**Fig.5 Normalized Transient Response**

**Fig.6 Maximum Safe Operation Area**

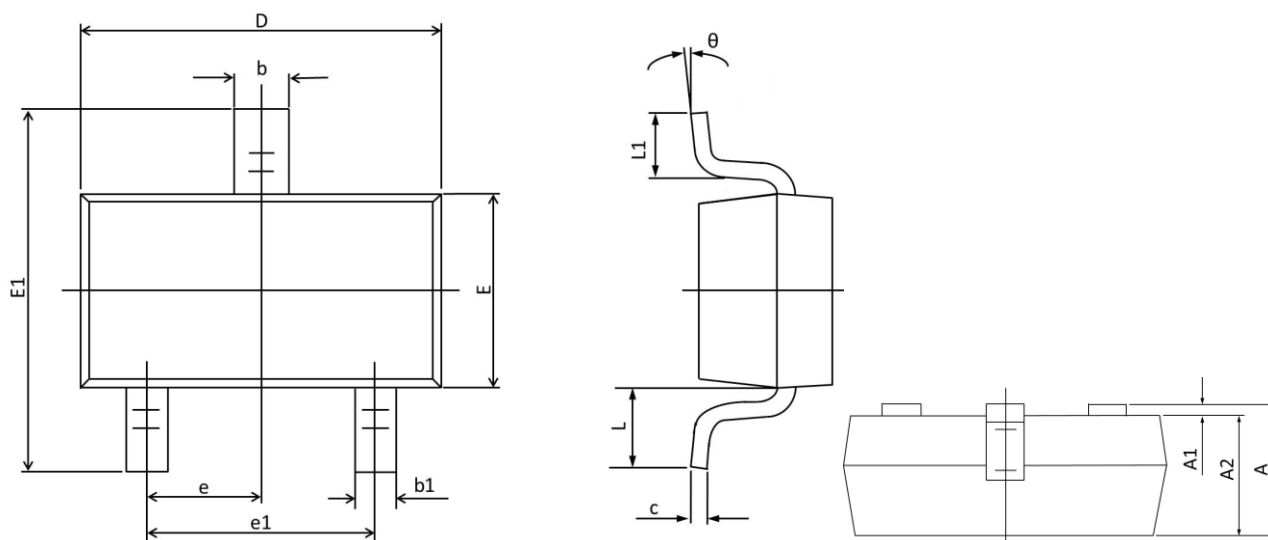


**Fig.7 Switching Time Waveform**



**Fig.8 Gate Charge Waveform**

## SOT523 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	0.900	0.700	0.035	0.028
A1	0.100	0.000	0.004	0.000
A2	0.800	0.700	0.031	0.028
b	0.350	0.250	0.014	0.010
b1	0.250	0.150	0.010	0.006
c	0.200	0.100	0.008	0.004
D	1.750	1.500	0.069	0.059
E	0.900	0.700	0.035	0.028
E1	1.750	1.400	0.069	0.055
e	0.5TYP.		0.02TYP.	
e1	1.100	0.900	0.043	0.035
L	0.460	0.300	0.018	0.012
L1	0.460	0.260	0.018	0.010
θ	8°	0°	8°	0°

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